

**MMST4126** 

#### 25V PNP SMALL SIGNAL TRANSISTOR IN SOT323

#### **Features**

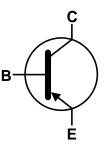
- BV<sub>CEO</sub> > -25V
- I<sub>C</sub> = -200mA Collector Current
- Epitaxial Planar Die Construction
- Ultra-Small Surface Mount Package
- Complementary NPN Type: MMST4124
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

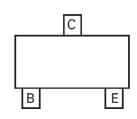
- Case: SOT323
- Case Material: Molded Plastic. "Green" Molding Compound.
   UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads.
   Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.006 grams (Approximate)







Device Symbol



Pin-Out Top View

April 2016

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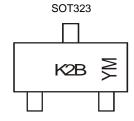
### Ordering Information (Note 4)

ĺ	Product	Status	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	MMST4126-7-F	Active	AEC-Q101	K2B	7	8	3,000

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



K2B = Product Type Marking Code YM = Date Code Marking Y or  $\underline{Y}$  = Year (ex: D = 2016) M or  $\overline{M}$  = Month (ex: 9 = September)

Date Code Key

Year	2010	) :	2011	2012	2013	2014	2015	2010	6 20	17 2	2018	2019	2020
Code	Χ		Υ	Z	Α	В	С	D	E	Ē	F	G	Н
Month	1	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	)	1	2	3	4	5	6	7	8	9	0	N	D



#### Absolute Maximum Ratings (@TA = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-25	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-25	V
Emitter-Base Voltage	V <sub>EBO</sub>	-4	V
Collector Current	Ic	-200	mA

### Thermal Characteristics (@TA = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_d$	200	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to +150	°C

### ESD Ratings (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	٧	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

### **Thermal Characteristics and Derating Information**

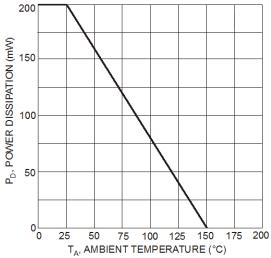


Fig. 1 Max Power Dissipation vs. Ambient Temperature

<sup>5.</sup> For a device mounted with the collector lead on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



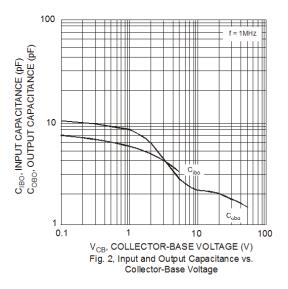
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

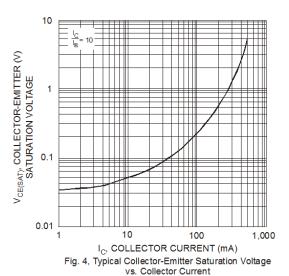
Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)						
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-25	_	V	$I_C = -10\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	-25	_	V	$I_C = -1 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	5		V	$I_E = -10\mu A, I_C = 0$	
Collector Base Cut-Off Current	I <sub>CBO</sub>		-50	nA	$V_{CB} = -20V, I_{E} = 0$	
Collector Cut-Off Current	I <sub>EBO</sub>	_	-50	nA	$V_{EB} = 5V, I_{E} = 0$	
ON CHARACTERISTICS (Note 7)						
DC Current Gain	h <sub>FE</sub>	120	360		$I_C = -2.0 \text{mA}, V_{CE} = -1.0 \text{V}$	
DC Current Gain		60			$I_C = -50 \text{mA}, V_{CE} = -1.0 \text{V}$	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$		-0.40	V	$I_C = -50 \text{mA}, I_B = -5.0 \text{mA}$	
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>		-0.95	V	$I_C = -50 \text{mA}, I_B = -5.0 \text{mA}$	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	$C_{obo}$		4.5	pF	$V_{CB} = -5.0V$ , $f = 1.0MHz$ , $I_E = 0$	
Input Capacitance	C <sub>ibo</sub>		10	рF	$V_{EB} = -0.5V$ , $f = 1.0MHz$ , $I_{C} = 0$	
Small Signal Current Gain	h <sub>fe</sub>	120	480	_	$V_{CE} = 1.0V$ , $I_{C} = -2.0mA$ , $f = 1.0kHz$	
Current Gain-Bandwidth Product	f⊤	250	_	MHz	V <sub>CE</sub> = -20V, I <sub>C</sub> = -10mA, f = 100MHz	
Noise Figure	NF	_	4.0	dB	$V_{CE} = -5.0V$ , $I_{C} = -100\mu A$ , $R_{S} = 1.0k\Omega$ , $f = 1.0kHz$	

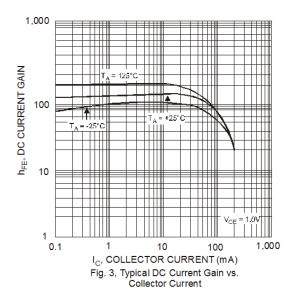
Note: 7. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.

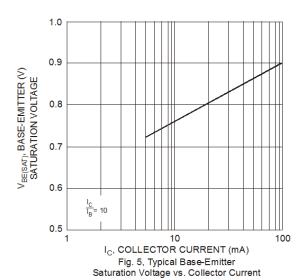


### Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)





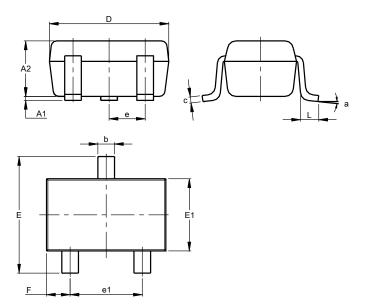






### **Package Outline Dimensions**

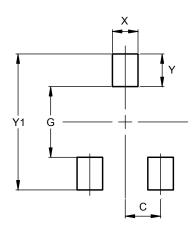
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT323							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.25	0.40	0.30				
С	0.10	0.18	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	C	).650 B	SC				
e1	1.20	1.40	1.30				
F	0.375	0.475	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
All	All Dimensions in mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.470
Y	0.600
Y1	2.500



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